- **2-V to 5.5-V V_{CC} Operation**
- **Max t_{pd} of 9.5 ns at 5 V**
- **Typical V_{OLP} (Output Ground Bounce) <0.8 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at V_{CC} = 3.3 V, T_A = 25°C**
- **Support Mixed-Mode Voltage Operation on All Ports**
- **Internal Look Ahead for Fast Counting**
- **Carry Output for n-Bit Cascading**

- **Synchronous Counting**
- **Synchronously Programmable**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

**SN54LV163A . . . J OR W PACKAGE
SN74LV163A . . . D, DB, DGV, NS, OR PW PACKAGE
(TOP VIEW)**

```
        ___
CLR [ 1      16 ] VCC
CLK [ 2      15 ] RCO
  A [ 3      14 ] QA
  B [ 4      13 ] QB
  C [ 5      12 ] QC
  D [ 6      11 ] QD
ENP [ 7      10 ] ENT
GND [ 8       9 ] LOAD
```
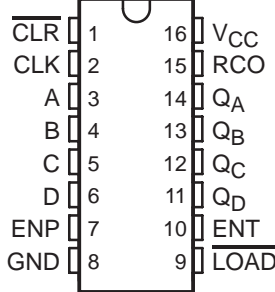
**SN74LV163A . . . RGY PACKAGE
(TOP VIEW)**

```
       CLR   VCC
        1     16
CLK [ 2          15 ] RCO
  A [ 3          14 ] QA
  B [ 4          13 ] QB
  C [ 5          12 ] QC
  D [ 6          11 ] QD
ENP [ 7          10 ] ENT
        8      9
       GND   LOAD
```
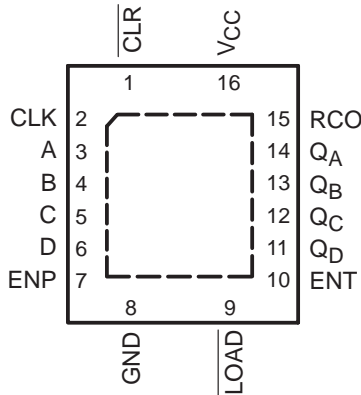
**SN54LV163A . . . FK PACKAGE
(TOP VIEW)**

```
     CLK CLR NC VCC RCO
      3   2   1  20  19
  A [ 4              18 ] QA
  B [ 5              17 ] QB
 NC [ 6              16 ] NC
  C [ 7              15 ] QC
  D [ 8              14 ] QD
      9  10  11  12  13
     ENP GND NC LOAD ENT
```

NC – No internal connection

description/ordering information

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
−40°C to 85°C	QFN – RGY	Reel of 1000	SN74LV163ARGYR	LV163A
	SOIC – D	Tube of 40	SN74LV163AD	LV163A
		Reel of 2500	SN74LV163ADR	
	SOP – NS	Reel of 2000	SN74LV163ANSR	74LV163A
	SSOP – DB	Reel of 2000	SN74LV163ADBR	LV163A
	TSSOP – PW	Tube of 90	SN74LV163APW	LV163A
		Reel of 2000	SN74LV163APWR	
		Reel of 250	SN74LV163APWT	
	TVSOP – DGV	Reel of 2000	SN74LV163ADGVR	LV163A
−55°C to 125°C	CDIP – J	Tube of 25	SNJ54LV163AJ	SNJ54LV163AJ
	CFP – W	Tube of 150	SNJ54LV163AW	SNJ54LV163AW
	LCCC – FK	Tube of 55	SNJ54LV163AFK	SNJ54LV163AFK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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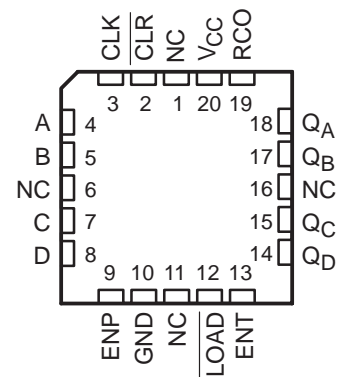## description/ordering information (continued)

The 'LV163A devices are 4-bit synchronous binary counters designed for 2-V to 5.5-V V_{CC} operation.

These synchronous, presettable counters feature an internal carry look ahead for application in high-speed counting designs. The 'LV163A devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

The clear function for the 'LV163A devices is synchronous. A low level at the clear ($\overline{CLR}$) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to $\overline{CLR}$ to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with Q_A high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or $\overline{LOAD}$) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.
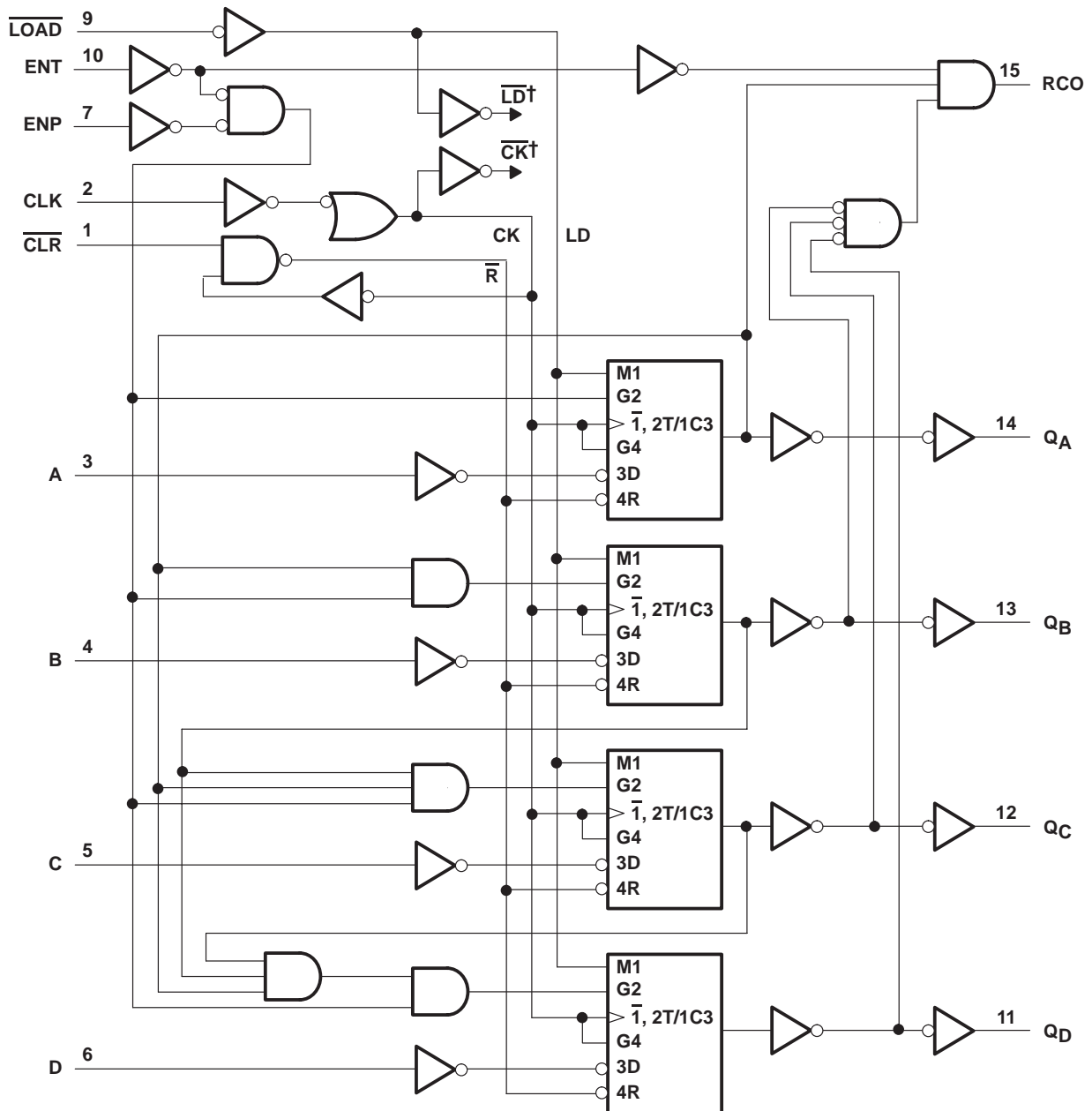
FUNCTION TABLE

INPUTS					OUTPUTS				FUNCTION
$\overline{CLR}$	$\overline{LOAD}$	ENP	ENT	CLK	$\overline{QA}$	QB	QC	QD	
L	X	X	X	X	L	L	L	L	Reset to "0"
H	L	X	X		A	B	C	D	Preset data
H	H	X	L		No change				No count
H	H	L	X		No change				No count
H	H	H	H		Count up				Count
H	X	X	X		No change				No count

logic diagram (positive logic)

LOAD 9

ENT 10

ENP 7

$\overline{LD}$†

$\overline{CK}$†

CLK 2

CLR 1

CK

LD

$\overline{R}$

RCO 15

M1
G2
> 1, 2T/1C3
G4
3D
4R

A 3

Q_A 14

M1
G2
> 1, 2T/1C3
G4
3D
4R

B 4

Q_B 13

M1
G2
> 1, 2T/1C3
G4
3D
4R

C 5

Q_C 12

M1
G2
> 1, 2T/1C3
G4
3D
4R

D 6

Q_D 11

† For simplicity, routing of complementary signals $\overline{LD}$ and $\overline{CK}$ is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

Pin numbers shown are for the D, DB, DGV, J, NS, PW, RGY, and W packages.

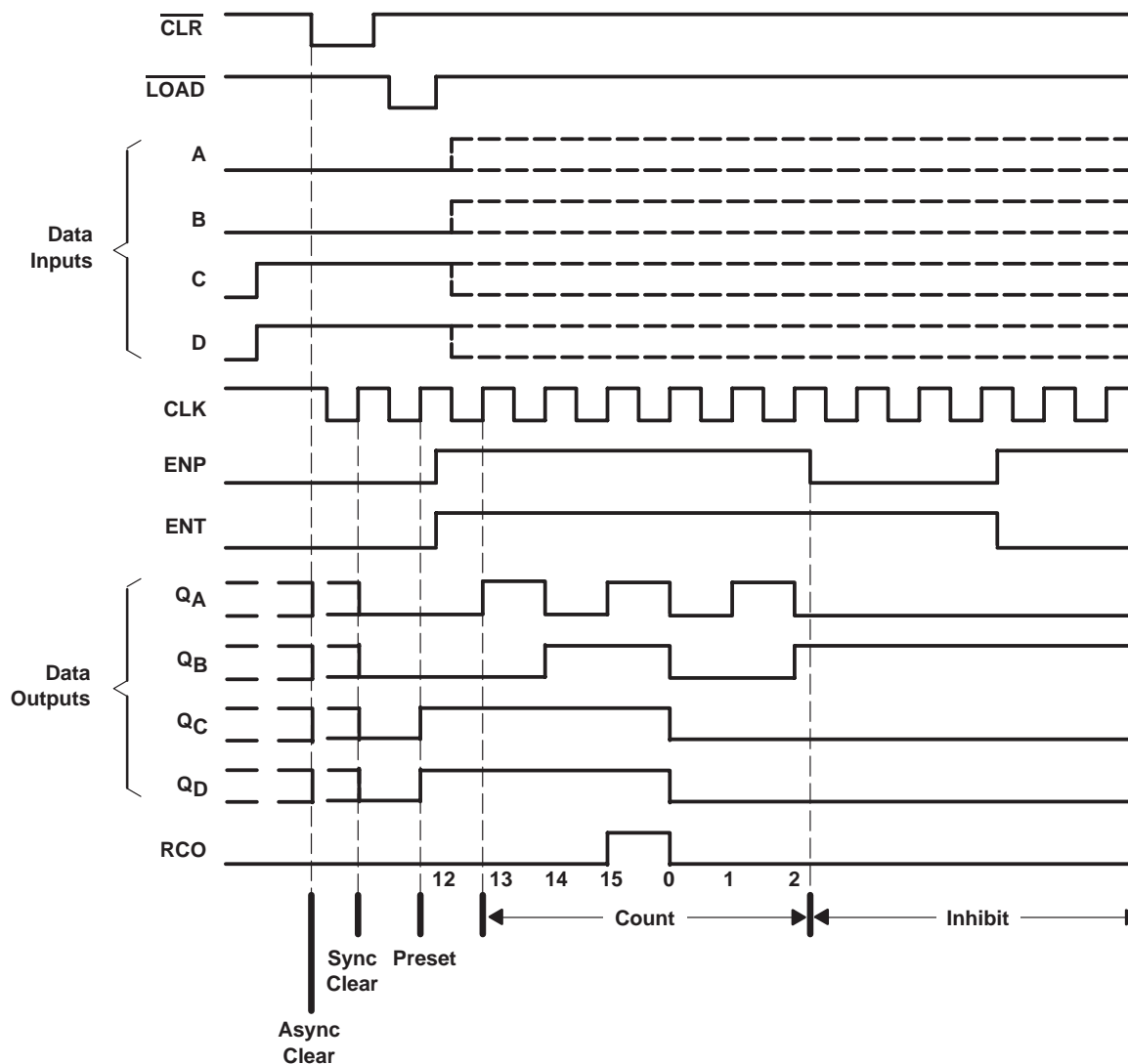## logic diagram, each D/T flip-flop (positive logic)
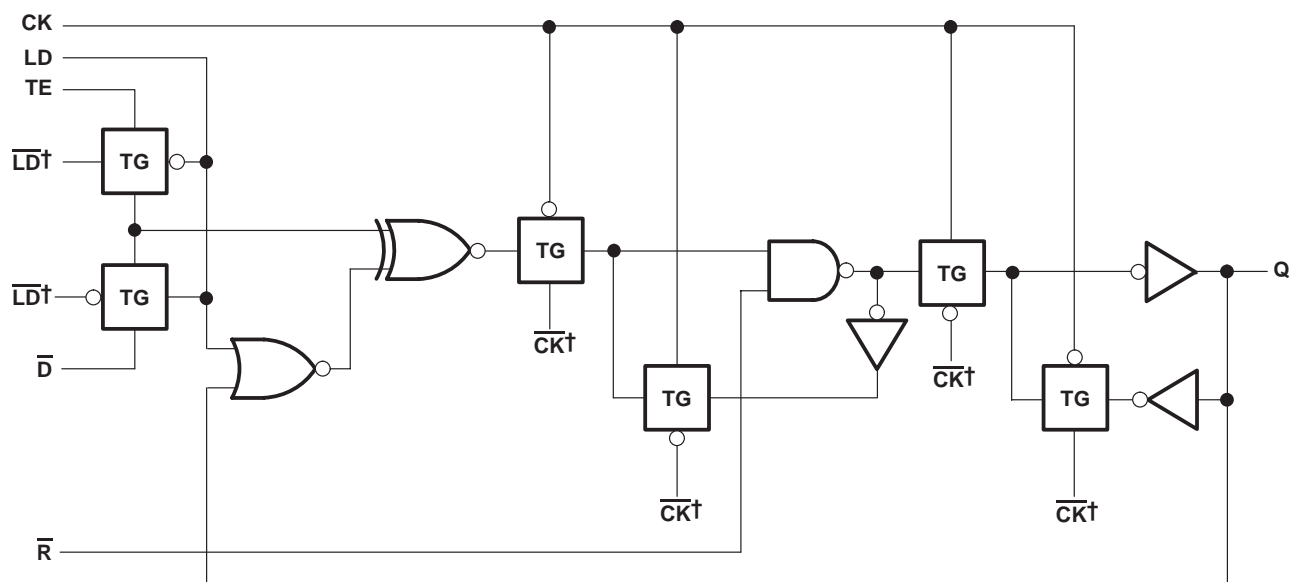
† The origins of $\overline{\text{LD}}$ and $\overline{\text{CK}}$ are shown in the overall logic diagram of the device.

typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

1. Clear outputs to zero (synchronous)

2. Preset to binary 12

3. Count to 13, 14, 15, 0, 1, and 2

4. Inhibit

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} . . . . −0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . −0.5 V to 7 V
Output voltage range applied in high or low state, V_O (see Notes 1 and 2) . . . . −0.5 V to V_{CC} + 0.5 V
Voltage range applied to any output in the power-off state, V_O (see Note 1) . . . . −0.5 V to 7 V
Input clamp current, I_{IK} (V_I < 0) . . . . −20 mA
Output clamp current, I_{OK} (V_O < 0) . . . . −50 mA
Continuous output current, I_O (V_O = 0 to V_{CC}) . . . . ±25 mA
Continuous current through V_{CC} or GND . . . . ±50 mA
Package thermal impedance, θ_{JA} (see Note 3): D package . . . . 73°C/W
(see Note 3): DB package . . . . 82°C/W
(see Note 3): DGV package . . . . 120°C/W
(see Note 3): NS package . . . . 64°C/W
(see Note 3): PW package . . . . 108°C/W
(see Note 4): RGY package . . . . 39°C/W
Storage temperature range, T_{stg} . . . . −65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
2. This value is limited to 5.5 V maximum.
3. The package thermal impedance is calculated in accordance with JESD 51-7.
4. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 5)

			SN54LV163A		SN74LV163A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		2	5.5	2	5.5	V
V_{IH}	High-level input voltage	V_{CC} = 2 V	1.5		1.5		V
		V_{CC} = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 3 V to 3.6 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
		V_{CC} = 4.5 V to 5.5 V	$V_{CC} \times 0.7$		$V_{CC} \times 0.7$		
V_{IL}	Low-level input voltage	V_{CC} = 2 V		0.5		0.5	V
		V_{CC} = 2.3 V to 2.7 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 3 V to 3.6 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
		V_{CC} = 4.5 V to 5.5 V		$V_{CC} \times 0.3$		$V_{CC} \times 0.3$	
V_I	Input voltage		0	5.5	0	5.5	V
V_O	Output voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current	V_{CC} = 2 V		−50		−50	µA
		V_{CC} = 2.3 V to 2.7 V		−2		−2	mA
		V_{CC} = 3 V to 3.6 V		−6		−6	
		V_{CC} = 4.5 V to 5.5 V		−12		−12	
I_{OL}	Low-level output current	V_{CC} = 2 V		50		50	µA
		V_{CC} = 2.3 V to 2.7 V		2		2	mA
		V_{CC} = 3 V to 3.6 V		6		6	
		V_{CC} = 4.5 V to 5.5 V		12		12	
$\Delta t/\Delta v$	Input transition rise or fall rate	V_{CC} = 2.3 V to 2.7 V		200		200	ns/V
		V_{CC} = 3 V to 3.6 V		100		100	
		V_{CC} = 4.5 V to 5.5 V		20		20	
T_A	Operating free-air temperature		−55	125	−40	85	°C

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V_{CC}	SN54LV163A			SN74LV163A			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
V_{OH}	I_{OH} = −50 µA	2 V to 5.5 V	V_{CC}−0.1			V_{CC}−0.1			V
	I_{OH} = −2 mA	2.3 V	2			2			
	I_{OH} = −6 mA	3 V	2.48			2.48			
	I_{OH} = −12 mA	4.5 V	3.8			3.8			
V_{OL}	I_{OL} = 50 µA	2 V to 5.5 V			0.1			0.1	V
	I_{OL} = 2 mA	2.3 V			0.4			0.4	
	I_{OL} = 6 mA	3 V			0.44			0.44	
	I_{OL} = 12 mA	4.5 V			0.55			0.55	
I_I	V_I = 5.5 V or GND	0 to 5.5 V			±1			±1	µA
I_{CC}	V_I = V_{CC} or GND, I_O = 0	5.5 V			20			20	µA
I_{off}	V_I or V_O = 0 to 5.5 V	0			5			5	µA
C_i	V_I = V_{CC} or GND	3.3 V		1.8			1.8		pF

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SCLS405F – APRIL 1998 – REVISED APRIL 2005

timing requirements over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV163A		SN74LV163A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low		7		7		7		ns
t_{su}	Setup time before CLK↑	$\overline{CLR}$	6		6		6		ns
		Data (A, B, C, and D)	7.5		8.5		8.5		
		ENP, ENT	9.5		11		11		
		$\overline{LOAD}$ low	10		11.5		11.5		
t_h	Hold time, all synchronous inputs after CLK↑		1.5		1.5		1.5		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV163A		SN74LV163A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low		5		5		5		ns
t_{su}	Setup time before CLK↑	$\overline{CLR}$	4		4		4		ns
		Data (A, B, C, and D)	5.5		6.5		6.5		
		ENP, ENT	7.5		9		9		
		$\overline{LOAD}$ low	8		9.5		9.5		
t_h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

timing requirements over recommended operating free-air temperature range, V_{CC} = 5 V ± 0.5 V (unless otherwise noted) (see Figure 1)

			T_A = 25°C		SN54LV163A		SN74LV163A		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t_w	Pulse duration, CLK high or low		5		5		5		ns
t_{su}	Setup time before CLK↑	$\overline{CLR}$	3.5		3.5		3.5		ns
		Data (A, B, C, and D)	4.5		4.5		4.5		
		ENP, ENT	5		6		6		
		$\overline{LOAD}$ low	5		6		6		
t_h	Hold time, all synchronous inputs after CLK↑		1		1		1		ns

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 2.5 V $\pm$ 0.2 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25°C$			SN54LV163A		SN74LV163A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	50*	115*		40*		40		MHz
			C_L = 50 pF	30	90		25		25		
t_{pd}	CLK	Q	C_L = 15 pF		8.5*	16.2*	1*	19.5*	1	19.5	ns
		RCO (count mode)			9.1*	17*	1*	20.5*	1	20.5	
		RCO (preset mode)			12.1*	20.6*	1*	24.5*	1	24.5	
	ENT	RCO			8.7*	15.7*	1*	19*	1	19	
t_{pd}	CLK	Q	C_L = 50 pF		11	19.2	1	22.5	1	22.5	ns
		RCO (count mode)			11.9	20	1	23.5	1	23.5	
		RCO (preset mode)			14.6	23.6	1	27.5	1	27.5	
	ENT	RCO			11.7	18.7	1	22	1	22	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

switching characteristics over recommended operating free-air temperature range, V_{CC} = 3.3 V $\pm$ 0.3 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25°C$			SN54LV163A		SN74LV163A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	80*	160*		70*		70		MHz
			C_L = 50 pF	55	125		50		50		
t_{pd}	CLK	Q	C_L = 15 pF		6.2*	12.8*	1*	15*	1	15	ns
		RCO (count mode)			6.8*	13.6*	1*	16*	1	16	
		RCO (preset mode)			8.8*	17.2*	1*	20*	1	20	
	ENT	RCO			6.5*	12.3*	1*	14.5*	1	14.5	
t_{pd}	CLK	Q	C_L = 50 pF		8	16.3	1	18.5	1	18.5	ns
		RCO (count mode)			8.8	17.1	1	19.5	1	19.5	
		RCO (preset mode)			10.7	20.7	1	23.5	1	23.5	
	ENT	RCO			8.2	15.8	1	18	1	18	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

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switching characteristics over recommended operating free-air temperature range, V_{CC} = 5 V $\pm$ 0.5 V (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	T_A = 25°C			SN54LV163A		SN74LV163A		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
f_{max}			C_L = 15 pF	135*	210*		115*		115		MHz
			C_L = 50 pF	95	160		85		85		
t_{pd}	CLK	Q	C_L = 15 pF		4.7*	8.1*	1*	9.5*	1	9.5	ns
		RCO (count mode)			5.2*	8.1*	1*	9.5*	1	9.5	
		RCO (preset mode)			6.4*	10.3*	1*	12*	1	12	
	ENT	RCO			4.9*	8.1*	1*	9.5*	1	9.5	
t_{pd}	CLK	Q	C_L = 50 pF		6.1	10.1	1	11.5	1	11.5	ns
		RCO (count mode)			6.6	10.1	1	11.5	1	11.5	
		RCO (preset mode)			7.8	12.3	1	14	1	14	
	ENT	RCO			6.3	10.1	1	11.5	1	11.5	

* On products compliant to MIL-PRF-38535, this parameter is not production tested.

noise characteristics, V_{CC} = 3.3 V, C_L = 50 pF, T_A = 25°C (see Note 6)

PARAMETER		SN74LV163A			UNIT
		MIN	TYP	MAX	
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.3	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		−0.2	−0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

NOTE 6:   Characteristics are for surface-mount packages only.

operating characteristics, T_A = 25°C

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	C_L = 50 pF, f = 10 MHz	3.3 V	23.8	pF
			5 V	26	

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PARAMETER MEASUREMENT INFORMATION

TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

From Output Under Test — Test Point — C_L (see Note A)

LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

From Output Under Test — C_L (see Note A) — $R_L = 1 \text{ k}\Omega$ — S1 — V_{CC} / Open / GND

LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS

VOLTAGE WAVEFORMS PULSE DURATION

Input — t_w — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

VOLTAGE WAVEFORMS SETUP AND HOLD TIMES

Timing Input — 50% V_{CC} — V_{CC} / 0 V
t_{su} — t_h
Data Input — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V

VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS

Input — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V
t_{PLH} — t_{PHL}
In-Phase Output — 50% V_{CC} — 50% V_{CC} — V_{OH} / V_{OL}
t_{PHL} — t_{PLH}
Out-of-Phase Output — 50% V_{CC} — 50% V_{CC} — V_{OH} / V_{OL}

VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

Output Control — 50% V_{CC} — 50% V_{CC} — V_{CC} / 0 V
t_{PZL} — t_{PLZ}
Output Waveform 1 S1 at V_{CC} (see Note B) — 50% V_{CC} — $\approx V_{CC}$ / V_{OL} + 0.3 V — V_{OL}
t_{PZH} — t_{PHZ}
Output Waveform 2 S1 at GND (see Note B) — 50% V_{CC} — V_{OH} − 0.3 V — V_{OH} / ≈ 0 V

NOTES: A. C_L includes probe and jig capacitance.
   B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
   C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 1 MHz, Z_O = 50 Ω, t_r ≤ 3 ns, t_f ≤ 3 ns.
   D. The outputs are measured one at a time, with one input transition per measurement.
   E. t_{PLZ} and t_{PHZ} are the same as t_{dis}.
   F. t_{PZL} and t_{PZH} are the same as t_{en}.
   G. t_{PHL} and t_{PLH} are the same as t_{pd}.
   H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/Ball Finish	MSL Peak Temp [3]
SN74LV163AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADBR	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADBRE4	ACTIVE	SSOP	DB	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADGVR	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADGVRE4	ACTIVE	TVSOP	DGV	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ADRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ANSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ANSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APWT	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163APWTE4	ACTIVE	TSSOP	PW	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV163ARGYR	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LV163ARGYRG4	ACTIVE	QFN	RGY	16	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

[1] The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

[2] Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check
http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and

package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

[3] MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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DGV (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE**

24 PINS SHOWN
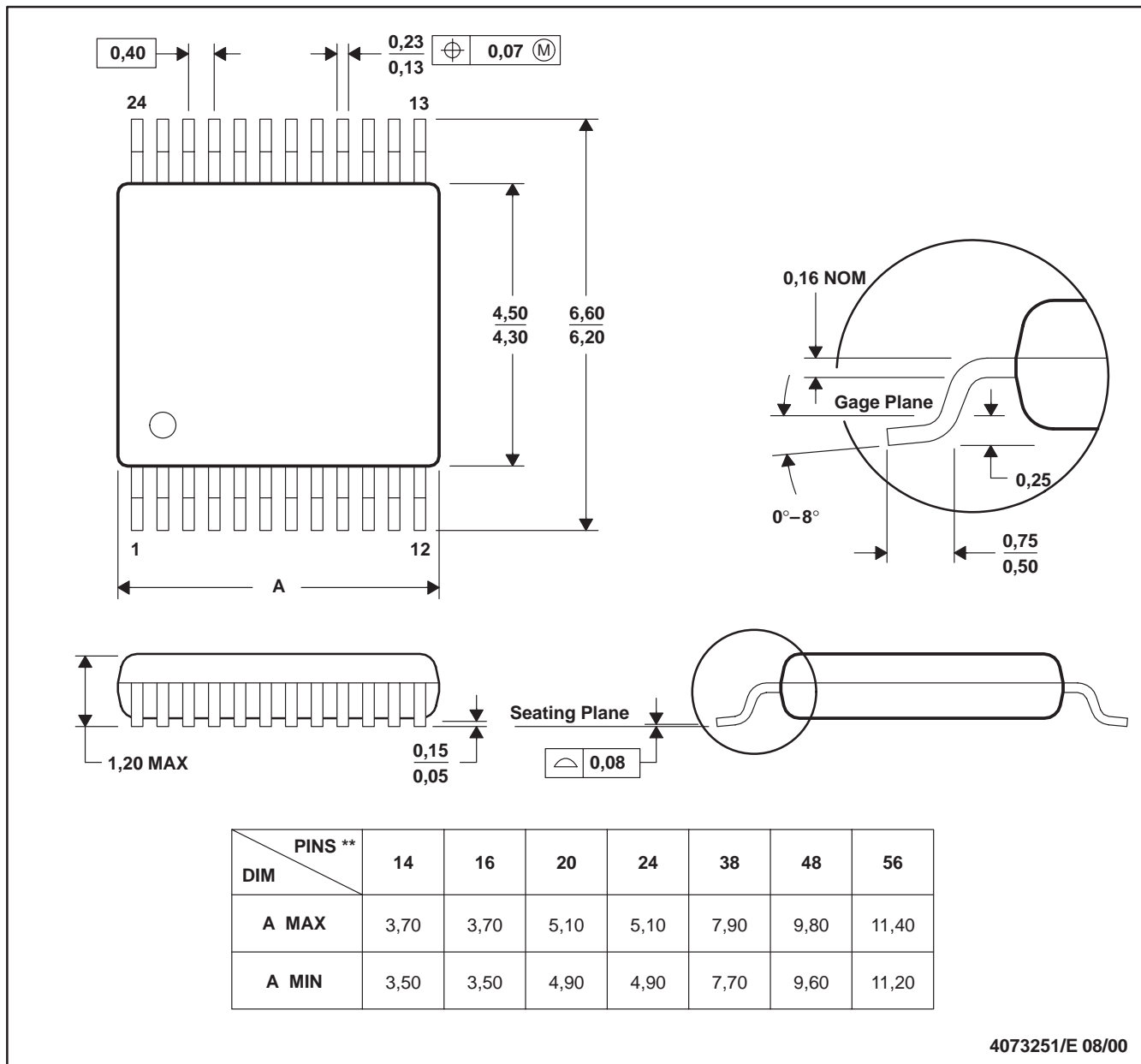
PINS ** DIM	14	16	20	24	38	48	56
A MAX	3,70	3,70	5,10	5,10	7,90	9,80	11,40
A MIN	3,50	3,50	4,90	4,90	7,70	9,60	11,20

4073251/E 08/00

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
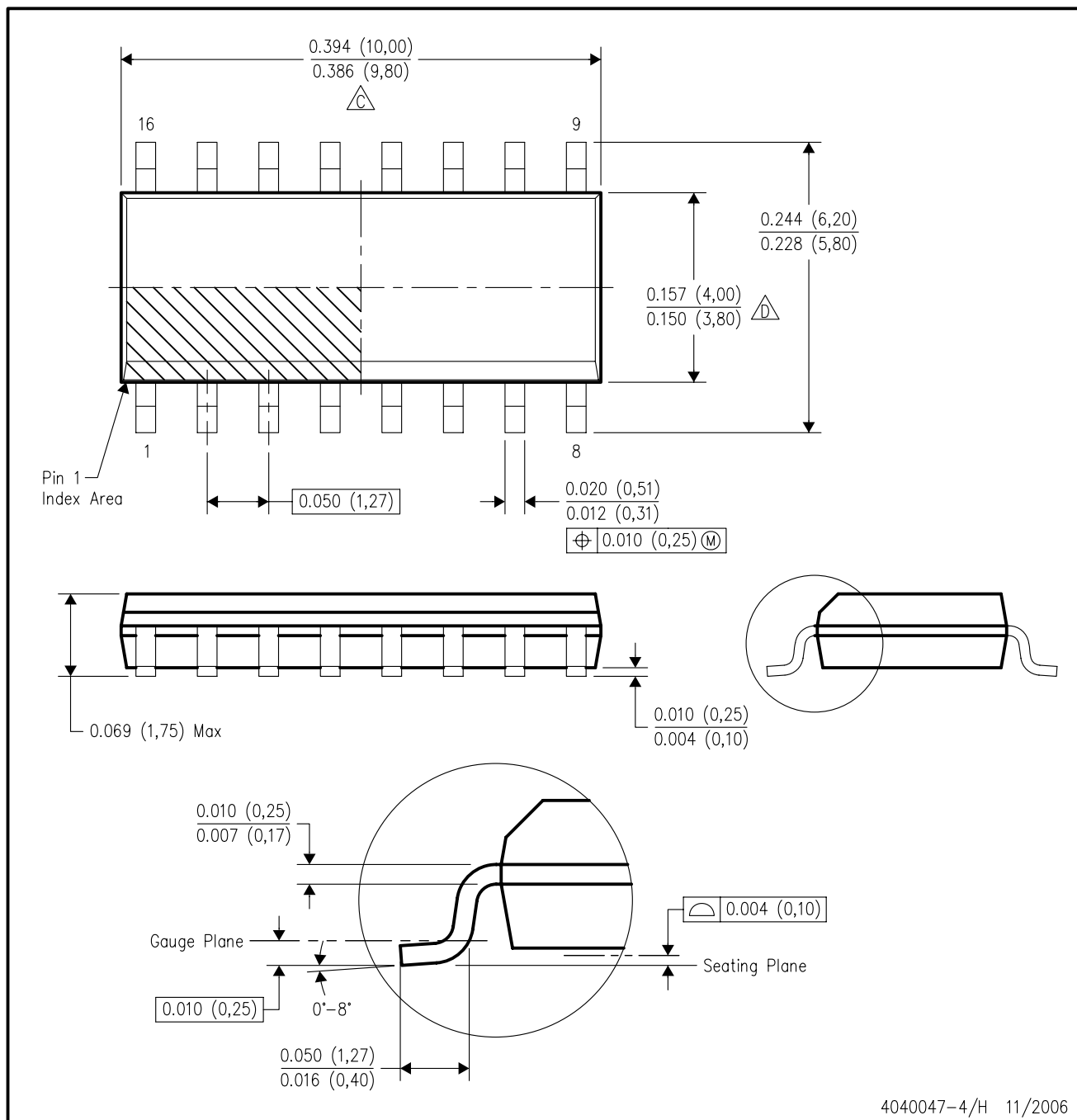D. Falls within JEDEC: 24/48 Pins – MO-153
                                    14/16/20/56 Pins – MO-194

TEXAS
INSTRUMENTS
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D (R−PDSO−G16)   **PLASTIC SMALL−OUTLINE PACKAGE**

0.394 (10,00)
0.386 (9,80)
⟨C⟩

16   9

0.244 (6,20)
0.228 (5,80)

0.157 (4,00)
0.150 (3,80) ⟨D⟩

1   8

Pin 1
Index Area

0.050 (1,27)

0.020 (0,51)
0.012 (0,31)

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

0.010 (0,25)
0.004 (0,10)

0.010 (0,25)
0.007 (0,17)

Gauge Plane

0.004 (0,10)

Seating Plane

0.010 (0,25)   0°–8°

0.050 (1,27)
0.016 (0,40)

4040047−4/H 11/2006

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed .006 (0,15) per end.
         D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
         E. Reference JEDEC MS−012 variation AC.

TEXAS INSTRUMENTS
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RGY (R−PQFP−N16)   **PLASTIC QUAD FLATPACK**

Pin 1 Index Area
Top and Bottom

$\frac{4,15}{3,85}$ A

B

$\frac{3,65}{3,35}$

15   10

16   9

1   8

2   7

0,20 Nominal
Lead Frame

Seating Plane

$\frac{1,00}{0,80}$

$\boxed{\frown}$ 0,08 C

$\frac{0,05}{0,00}$
Seating Height

C

2,50

0,50

16X $\frac{0,50}{0,30}$

1,50

2,05 $^{+0,10}_{-0,15}$

16X $\frac{0,30}{0,18}$

2,55 $^{+0,10}_{-0,15}$

⊕	0,10 Ⓜ	C	A	B
	0,05 Ⓜ	C		

Exposed Thermal Pad

Bottom View

4203539−3/G 04/2005

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
B. This drawing is subject to change without notice.
C. QFN (Quad Flatpack No−Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
F. Package complies to JEDEC MO−241 variation BB.

NS (R-PDSO-G)**   **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN

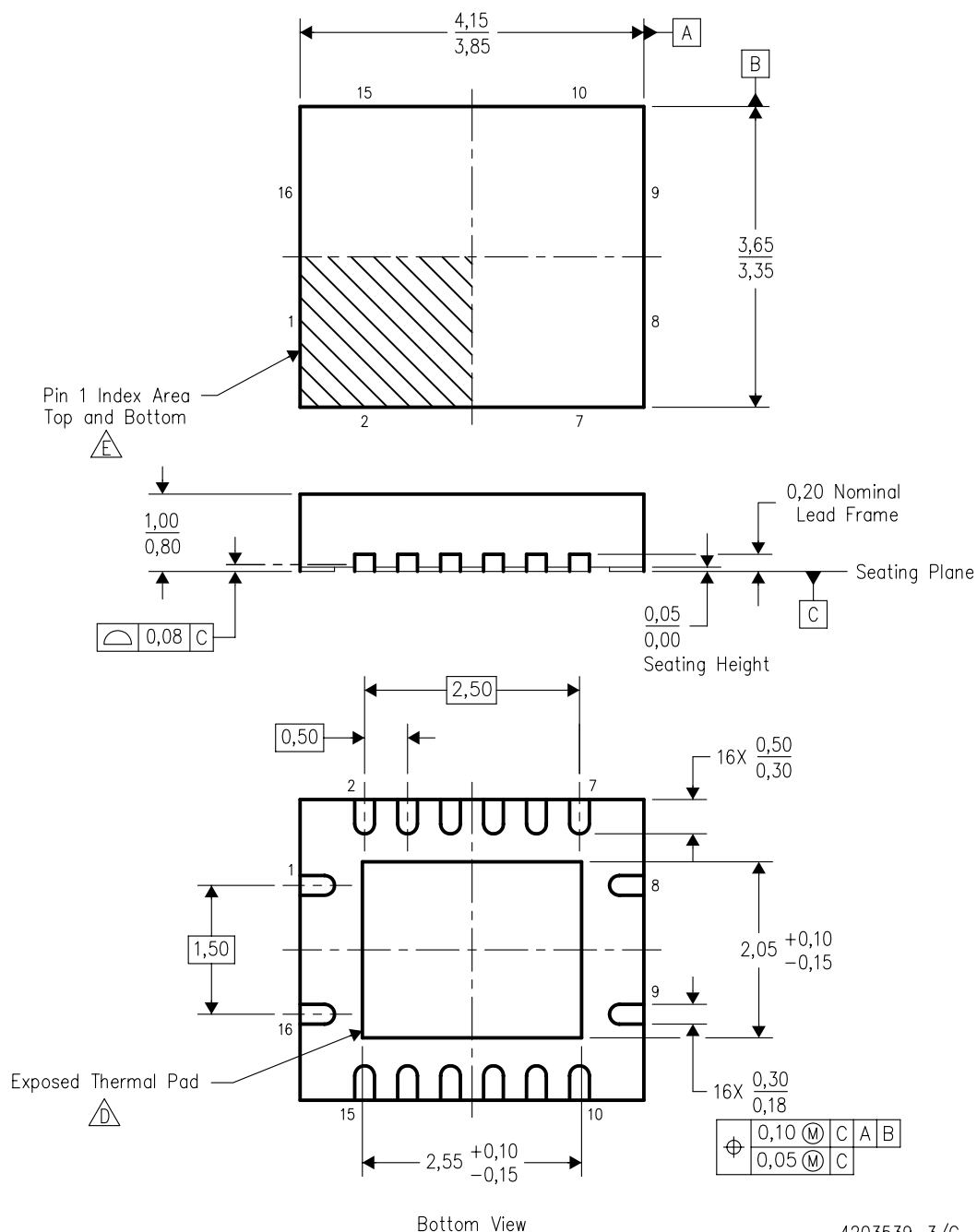| DIM	PINS ** 14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.
           B. This drawing is subject to change without notice.
           C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

DB (R-PDSO-G**)   **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN

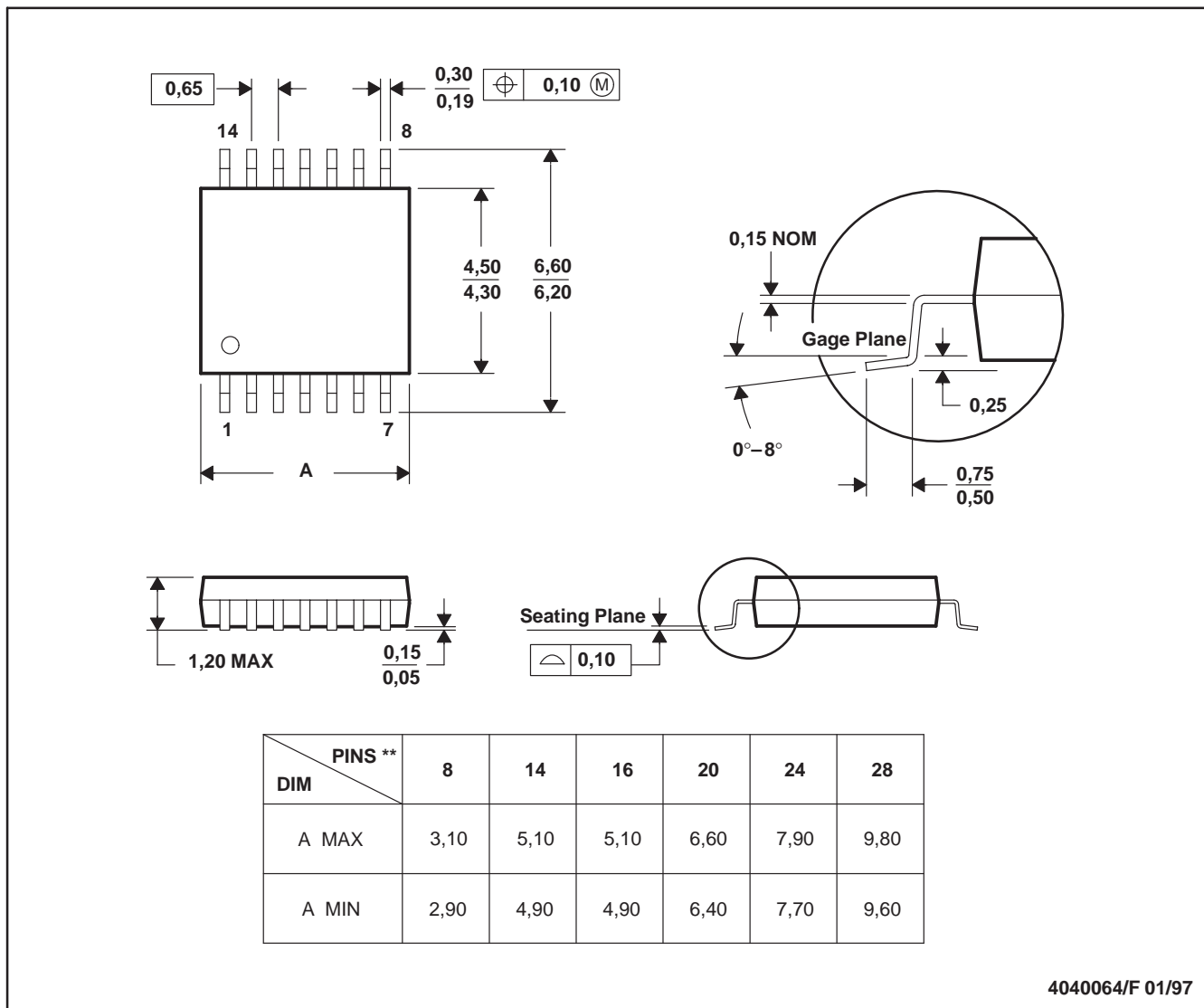| PINS ** DIM	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
   B. This drawing is subject to change without notice.
   C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
   D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN

0,65

$\dfrac{0,30}{0,19}$

⊕ 0,10 Ⓜ

14   8

$\dfrac{4,50}{4,30}$ $\dfrac{6,60}{6,20}$

1   7

A

0,15 NOM

Gage Plane

0°−8°

0,25

$\dfrac{0,75}{0,50}$

1,20 MAX

$\dfrac{0,15}{0,05}$

Seating Plane

⌒ 0,10

DIM \ PINS **	8	14	16	20	24	28
A MAX	3,10	5,10	5,10	6,60	7,90	9,80
A MIN	2,90	4,90	4,90	6,40	7,70	9,60

4040064/F 01/97

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-153

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Post Office Box 655303 Dallas, Texas 75265